



LIGITEK ELECTRONICS CO.,LTD.
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LED SMD



Lead-Free Parts

LG-197GBR-CT-3C2

DATA SHEET

DOC. NO : QW0905-LG-197GBR-CT-3C2_A

REV. : B

DATE : 12 - Jan. - 2018



Features:

1. Package in 8.0mm carrier tape on 7" diameter reel.
2. Compatible with automatic placement equipment.
3. Compatible with infrared and vapor phase reflow solder process.

Descriptions:

1. The LG-197 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
2. Besides, lightweight makes them ideal for miniature applications. etc.

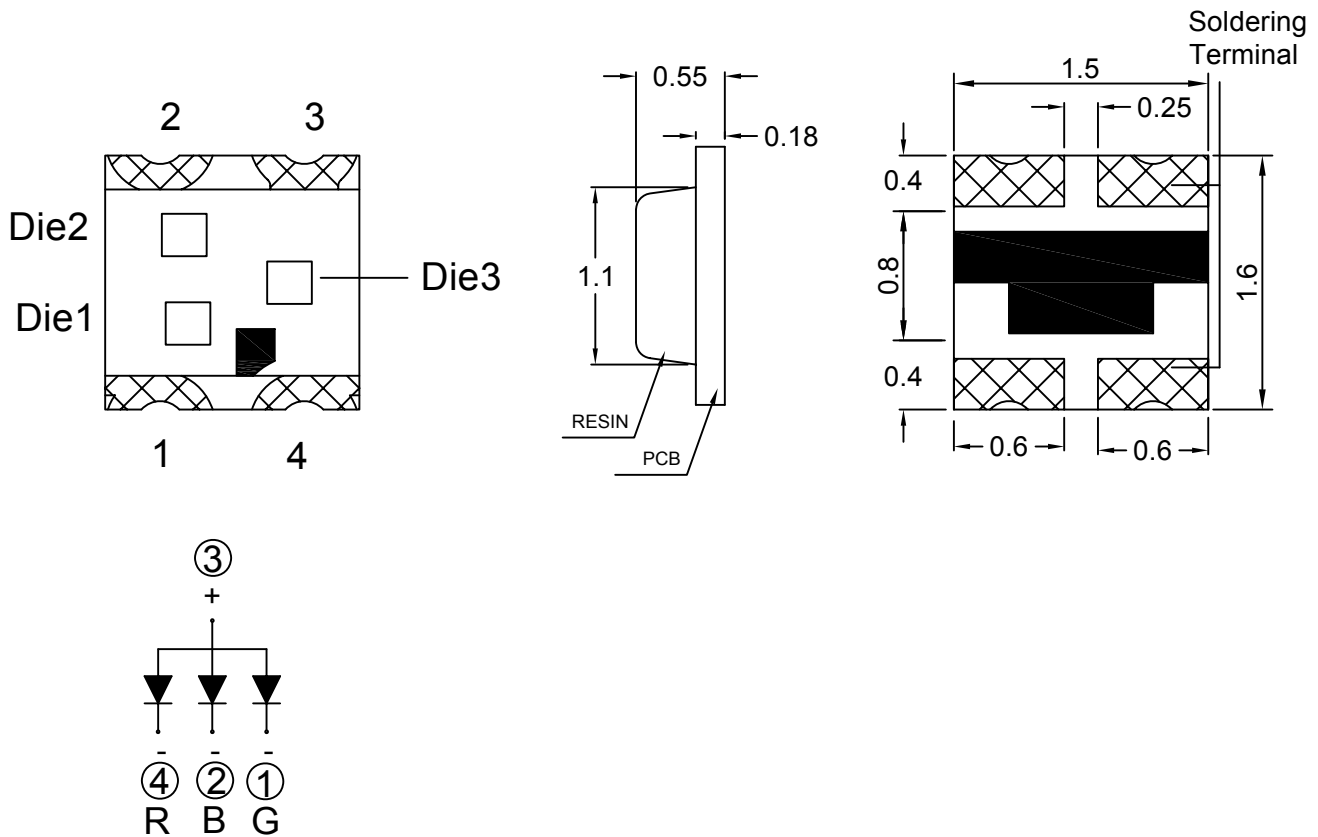
Applications:

1. Automotive : backlighting in dashboard and switch.
2. Telecommunication : indicator and backlighting in telephone and fax.
3. Flat backlight for LCD, switch and symbol
4. General use.

Device Selection Guide:

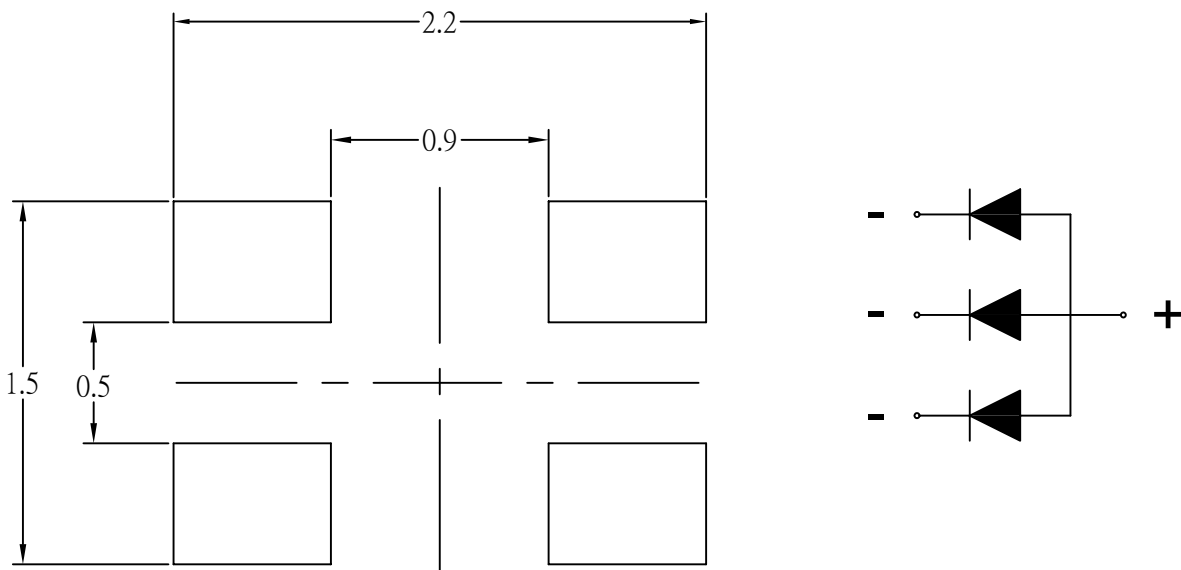
PART NO	MATERIAL	COLOR	
		Emitted	Lens
LG-197GBR-CT-3C2	AlGaInP	Red	Water Clear
	InGaN	Green	
	InGaN	Blue	

Package Dimensions



Note : 1.All dimension are in millimeter tolerance is ± 0.1 mm unless otherwise noted.
2.Specifications are subject to change without notice.

Recommended Soldering Pad Dimensions



Note : The tolerances unless mentioned is ± 0.1 mm, Angle ± 0.5 . Unit=mm.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Ratings			UNIT
		DGM	DBK	HRF	
Power Dissipation	PD	72	72	60	mW
Peak Forward Current Duty 1/10@10KHz	IFP	100	100	90	mA
Forward Current	IF	20	20	25	mA
Reverse Current @5V	Ir	50	50	10	μA
Electrostatic Discharge	ESD	500	500	2000	V
Operating Temperature	Topr	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +100			°C

Typical Electrical & Optical Characteristics (Ta=25°C)

Items	Symbol	Min.	Typ.	Max.	UNIT	CONDITION
Luminous Intensity	DGM	200	----	800	mcd	IF=20mA
	DBK	80	----	320		
	HRF	50	----	200		
Dominant Wavelength	DGM	515	----	535	nm	IF=20mA
	DBK	460	----	480		
	HRF	620	----	640		
Spectral Line Half-Width	DGM	----	36	----	nm	IF=20mA
	DBK	----	30	----		
	HRF	----	20	----		
Forward Voltage	DGM	2.8	----	3.6	V	IF=20mA
	DBK	2.8	----	3.6		
	HRF	1.5	----	2.4		
Viewing Angle	DGM	----	140	----	deg	IF=20mA
	DBK	----	140	----		
	HRF	----	140	----		

Luminous Intensity Classification

BIN CODE		Iv(mcd) at 20mA	
		Min.	Max.
DGM	S	200	320
	T	320	500
	U	500	800

BIN CODE		Iv(mcd) at 20mA	
		Min.	Max.
DBK	Q	80	125
	R	125	200
	S	200	320

BIN CODE		Iv(mcd) at 20mA	
		Min.	Max.
HRF	P	50	80
	Q	80	125
	R	125	200

Typical Electro-Optical Characteristics Curve

DGM CHIP

Fig.1 Forward current vs. Forward Voltage

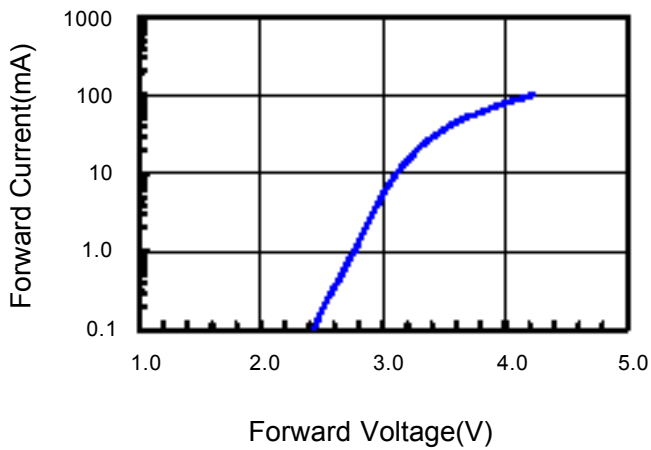


Fig.2 Relative Intensity vs. Forward Current

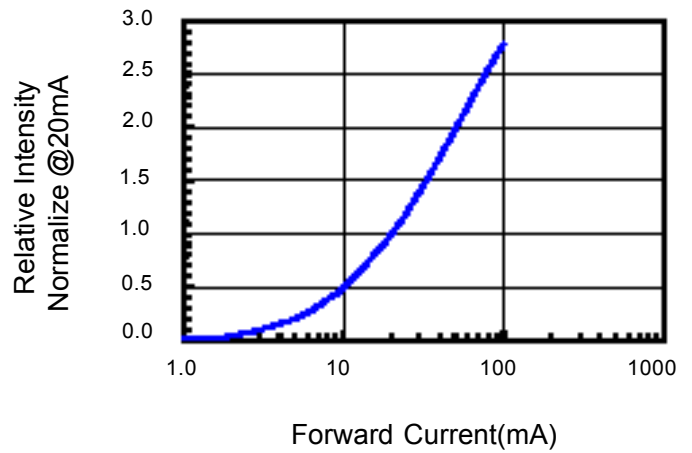


Fig.3 Forward Current vs. Temperature

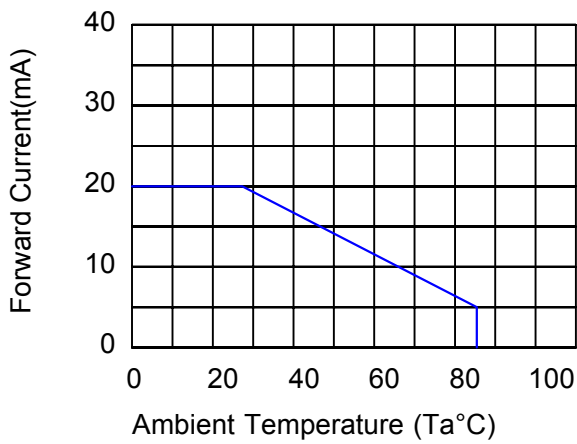


Fig.4 Relative Intensity vs. Temperature

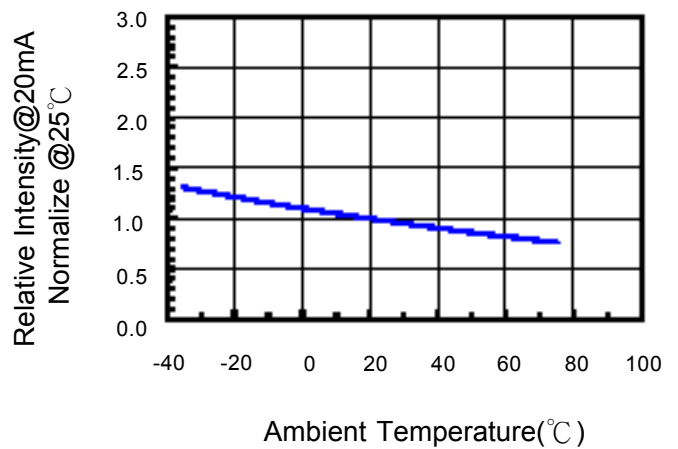


Fig.5 Relative Intensity vs. Wavelength

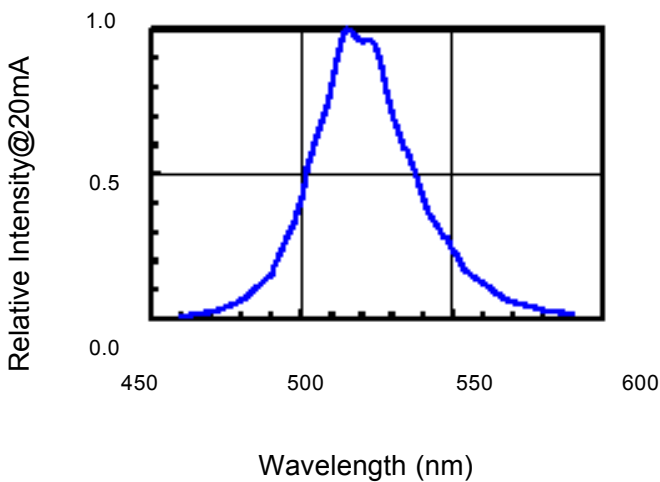
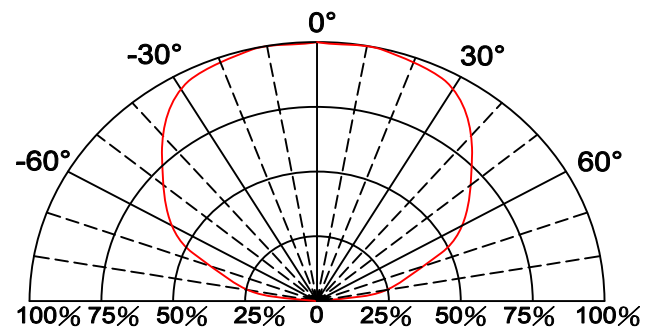


Fig.6 Directive Radiation



Typical Electro-Optical Characteristics Curve

DBK CHIP

Fig.1 Forward current vs. Forward Voltage

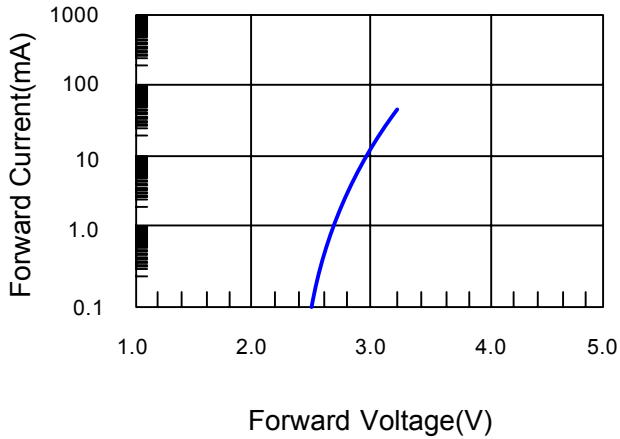


Fig.2 Relative Intensity vs. Forward Current

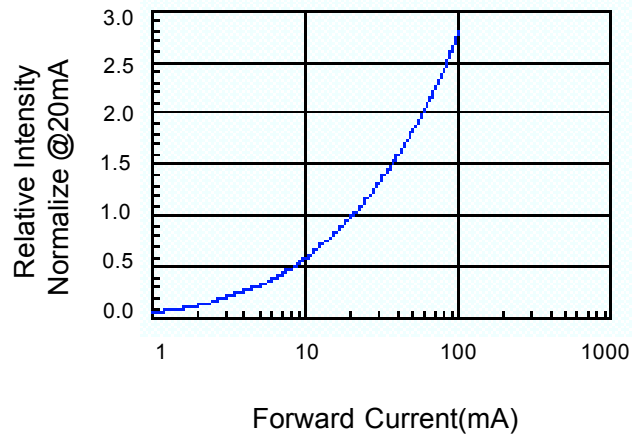


Fig.3 Forward Current vs. Temperature

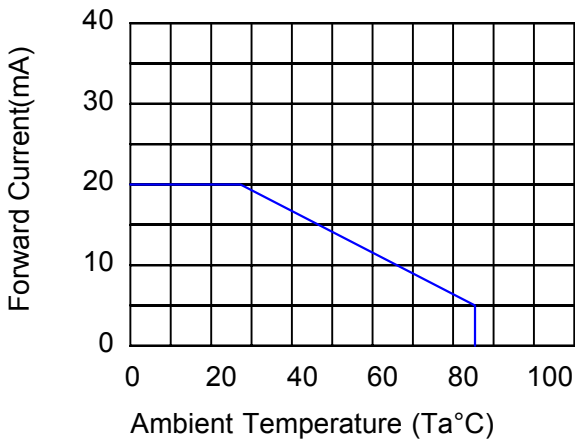


Fig.4 Relative Intensity vs. Temperature

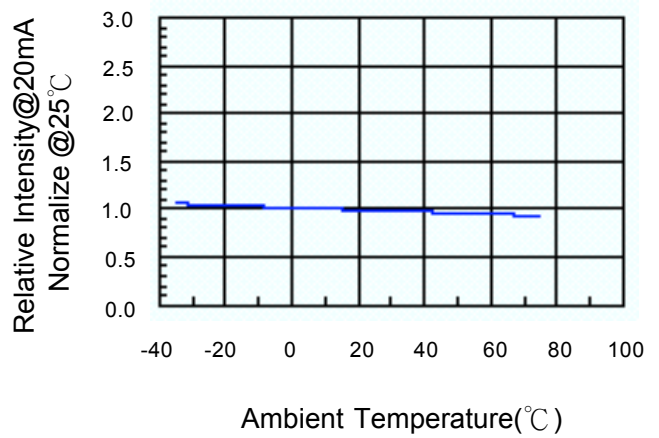


Fig.5 Relative Intensity vs. Wavelength

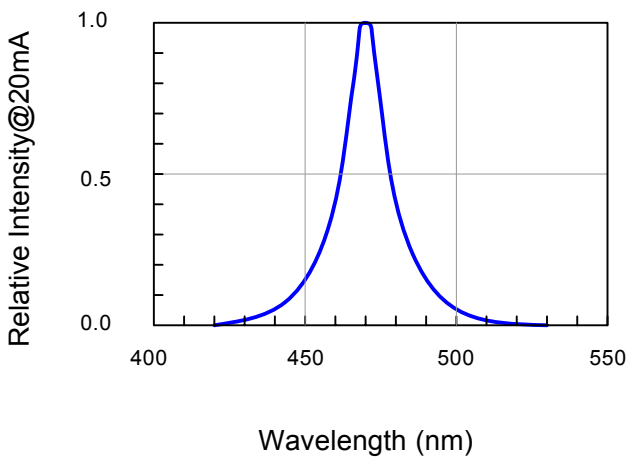
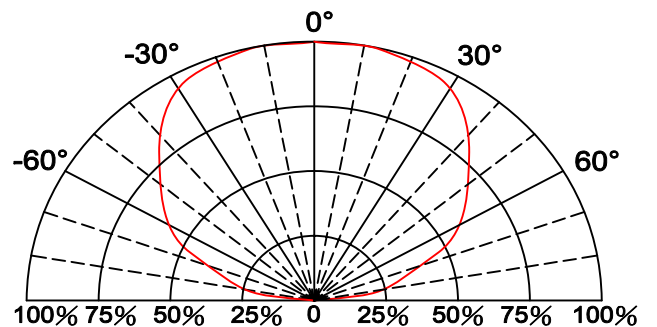


Fig.6 Directive Radiation



Typical Electro-Optical Characteristics Curve

HRF CHIP

Fig.1 Forward current vs. Forward Voltage

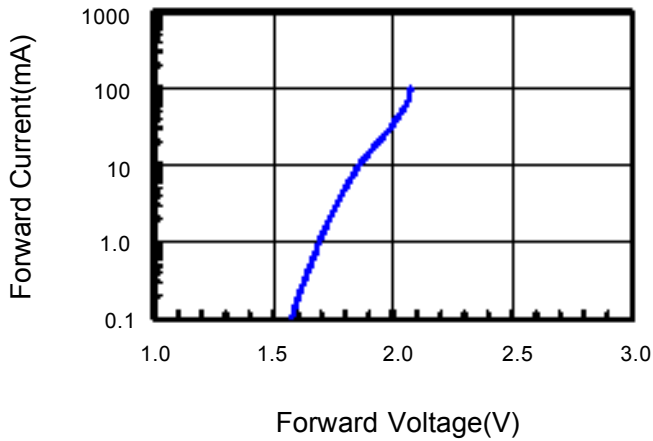


Fig.2 Relative Intensity vs. Forward Current

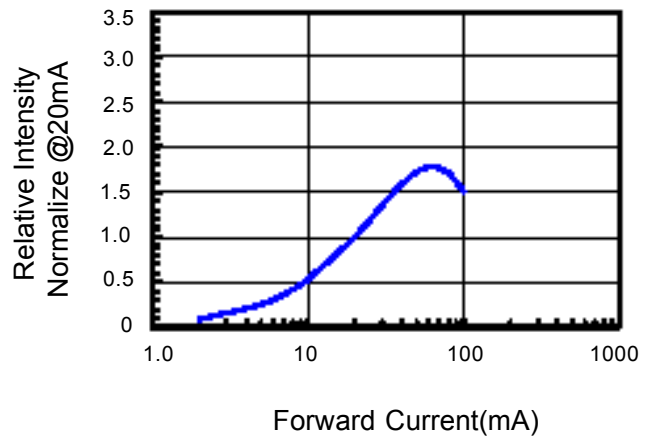


Fig.3 Forward Current vs. Temperature

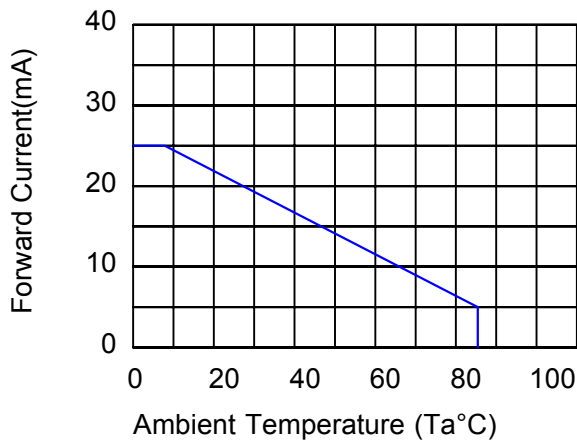


Fig.4 Relative Intensity vs. Temperature

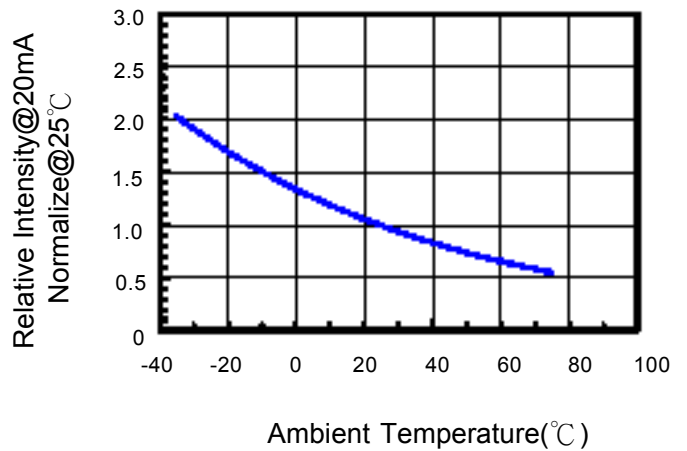


Fig.5 Relative Intensity vs. Wavelength

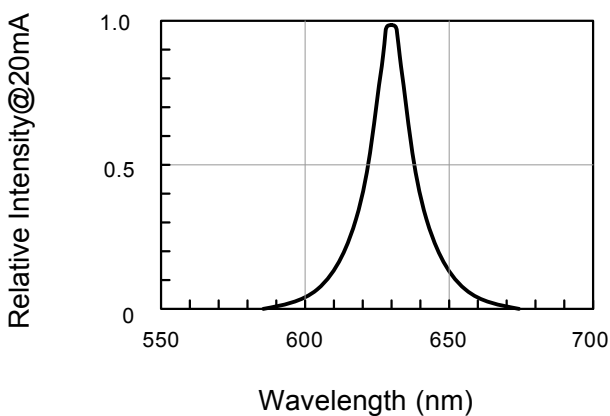
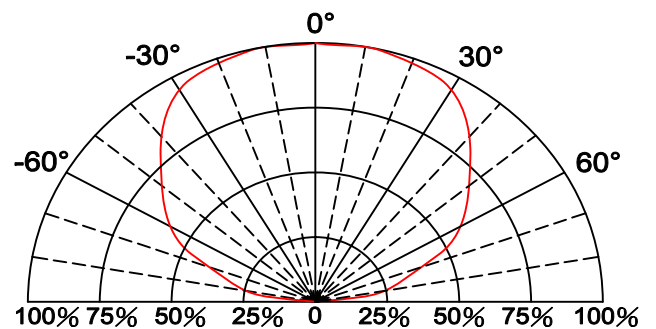
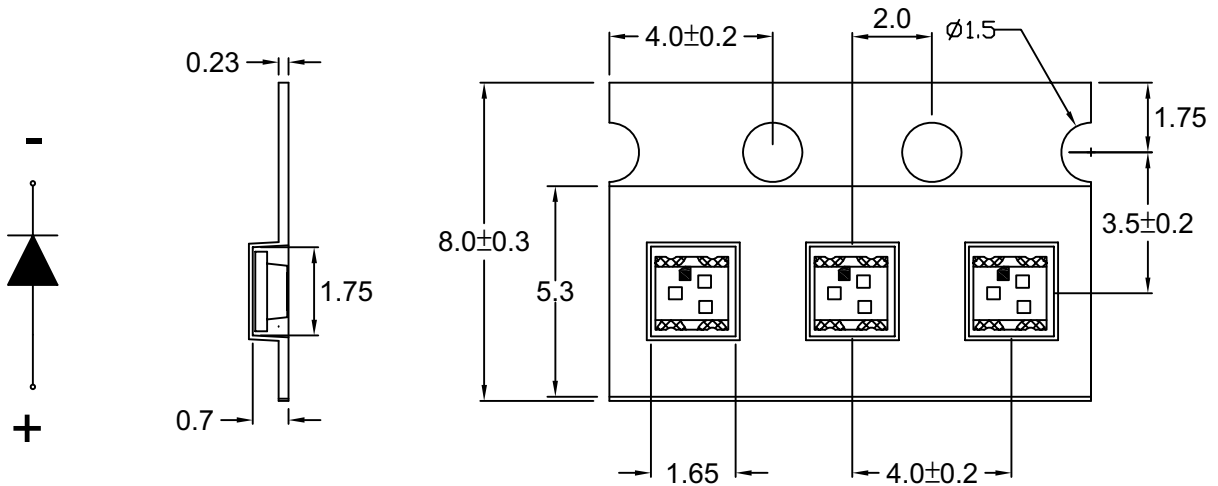


Fig.6 Directive Radiation

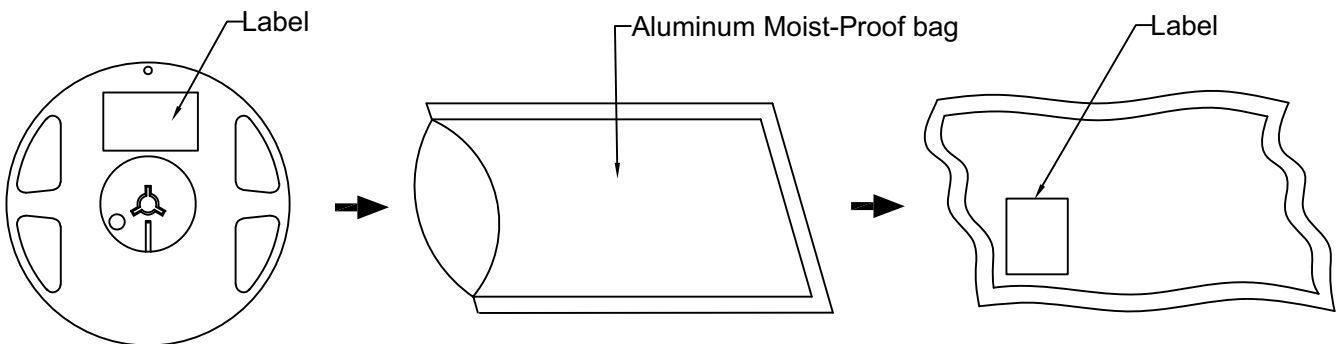


Carrier Tape Dimensions











Note : The tolerances unless mentioned is ± 0.1 mm, Angle ± 0.5 . Unit=mm.

Packing Specifications



Part No.	Description	Quantity/Reel
LG-197GBR-CT-3C2	8.0mm tape, 7" reel	4000 devices

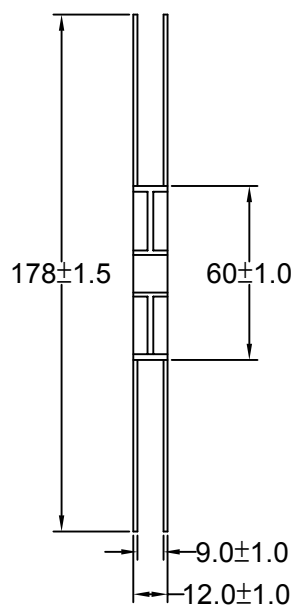
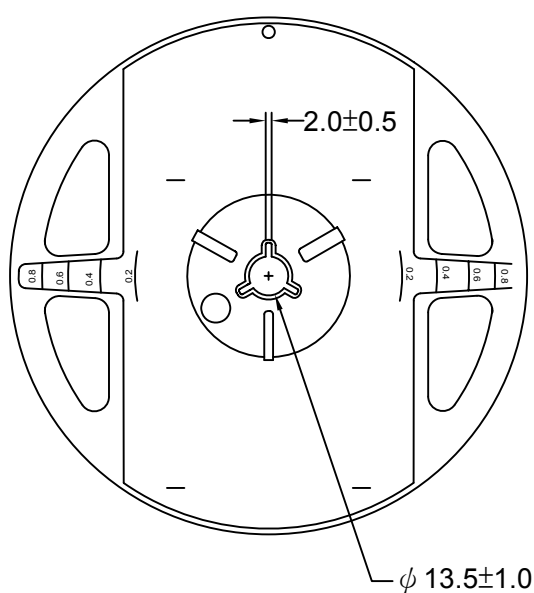
Label Explanation

 LIGITEK ELECTRONICS CO., LTD.	
PART :	 LG-197GBR-CT-3C2
LOT :	 GS11370168
QTY(PCS):	 4000
BIN/HUE :	 U-Q-P
	 VF:2.8-3.6
	 VF:2.8-3.6
	 VF:1.5-2.4

BIN : Luminous Intensity

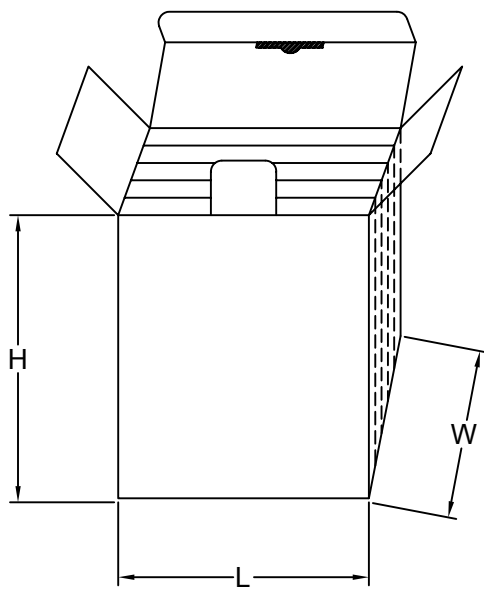
VF : Forward Voltage

Reel Dimensions

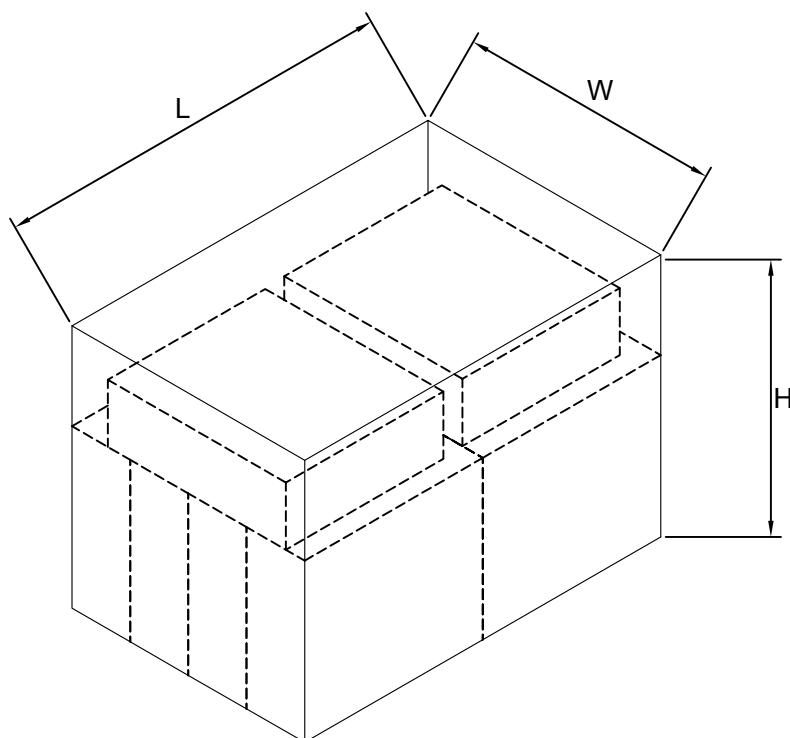


Box Explanation

1. 5 BAG / INNER BOX
2. INNER BOX SIZE : L X W X H 23cm X 8.5cm x 26cm

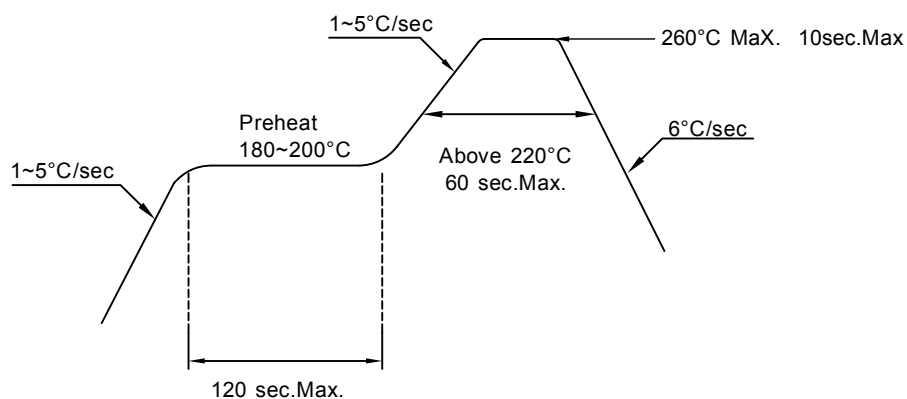


3. 10 INNER BOXES / CARTON
4. CARTON SIZE : L X W X H 58cm X 34cm x 35cm



Recommended Soldering Conditions**1. Hand Solder**

Basic spec is $\leq 280^{\circ}\text{C}$ 3 sec one time only.

3. PB-Free Reflow Solder**Note:**

- 1.Reflow soldering should not be done more than two times.
- 2.When soldering,do not put stress on the LEDs during heating.
- 3.After soldering,do not warp the circuit board.

Precautions For Use:**Storage time:**

1. Calculated shelf life before opening is 18 months at $< 30^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
2. After bag is opened, devices which will be subjected to reflow soldering or other high temperature processes must be
 - a) Assembled within one years in an environment of $\leq 30^{\circ}\text{C} / 60\%$ RH, or
 - b) Stored at ambient of 10% RH or less
3. Devices are required baking before assembly if:
 - a) Humidity Indicator Card reads $>10\%$ (for level 2a -5a) or $>60\%$ (for level 2) at ambient temperature $23\pm 5^{\circ}\text{C}$
 - b) 2.a) or 2.b) doesn't meet
4. If baking is required, devices should be baked for >72 hours at $60\pm 5^{\circ}\text{C} / 5\%$ RH. Performing baking only once, and using the baked devices within 72 hours.

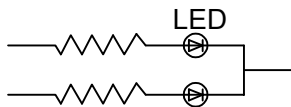
MSL LEVEL 2

Drive Method:

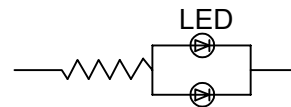
LED is a current operated device, and therefore, requires some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in series with the LED.

Consider worst case voltage variations than could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.

Circuit model A



Circuit model B



(A) Recommended circuit.

(B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling these LED. All devices, equipment and machinery must be properly grounded.

Reliability Test:

Classification	Test Item	Test Condition	Sample Size
Endurance Test	Operating Life Test	1.Ta=25°C 2.If=20mA 3.t=1000 hrs (-24hrs,+72hrs)	22
	High Temperature Storage Test	1.Ta=100°C±5°C 2.t=1000 hrs (-24hrs,+72hrs)	22
	Low Temperature Storage Test	1.Ta=-40°C±5°C 2.t=1000 hrs (-24hrs,+72hrs)	22
	High Temperature High Humidity Storage Test	1.Ta=85°C 2.RH=85% 3.t=1000hrs(-24hrs,+72hrs)	22
Environmental Test	Thermal Shock Test	1.Ta=100°C±5°C ~ -40°C±5°C 20min/ 10sec / 20min 2.total 100 cycles	22
	Temperature Cycling	1.100°C±5°C ~ -40°C±5°C 30mins / 5mins / 30mins 2.100 Cyeles	22
	IR Reflow	1.T=260°C Max. 10sec.Max. 2. 6 Min	22